

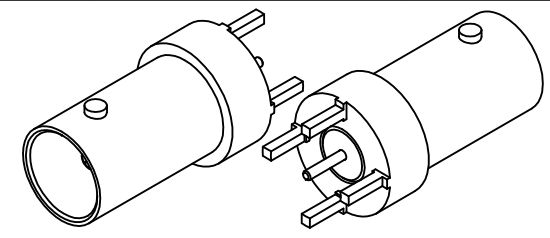
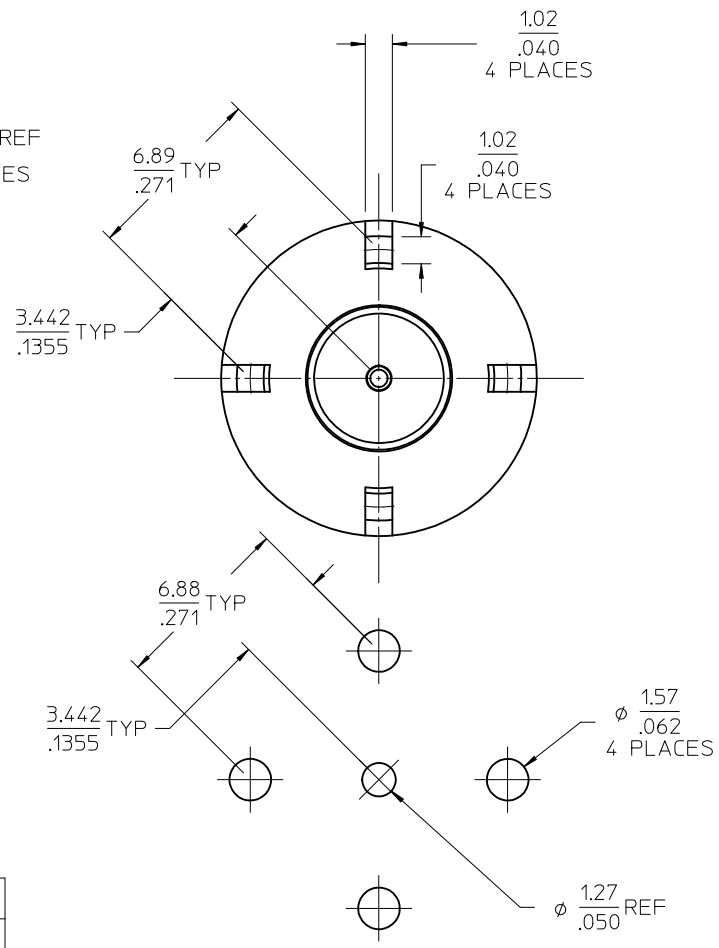
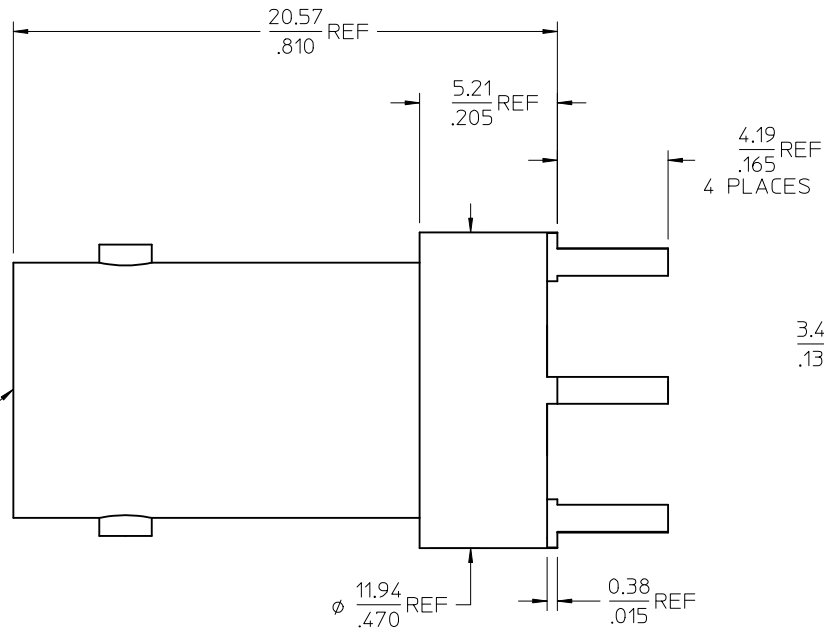
MATERIALS AND FINISHES

BODY, PRESS RING: BRASS
PLATED NICKEL

CONTACT: BERYLLIUM COPPER
PLATED GOLD

INSULATOR: TEFLON

75 OHM INTERFACE



73171-3231	ONE PER BAG
73171-3230	TRAY
PART NO.	PACKAGING

PS-89675-2020	PRODUCT SPECIFICATION
SPECIFICATION	DESCRIPTION

RECOMMENDED PCB LAYOUT

CHG: ADD -3231 EC NO: URF2011-0572 DRWN: JWIENER 2011/03/30 CHKD: SSS 2011/03/30 APPR: JWIENER 2011/04/01 B2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN	SCALE METRIC	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---		DRAWN BY AZR	DATE 2007/05/29	TITLE BNC JACK PCB 3GHZ 75 OHM VERTICAL BNC-J/PCB, EWR-3355		
		ANGULAR ± 2 °		CHECKED BY SSS	DATE 2007/05/29	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY JDW	DATE 2007/05/29	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-73171-323	SHEET NO. 1 OF 1

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